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IN THE ABSTRACT

Page 4, lines 2-9 have been amended as follows:

A housing for enclosing an electronic element of an electronic device ~~is provided. The housing~~ is formed of plastic material without electromagnetic waves shielding capability and ~~comprises~~ includes a first hole for injecting fluid of nonconductive, non-corrosive, and high heat transfer capability (e.g., silicon oil or hydro oil) or a semisolid substance having similar properties thereinto, a second hole for evacuating air, and two stop members inserted in the holes for sealing after the injection. The electronic element is adapted to be waterproof and vibration-proof, and has a predetermined heat dissipation capability.